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OFFER 2018 NANO 36 THIN FILM DEPOSITION SYSTEM

COMPANY	University of Nevada	REFERENCE #	SQ_162190MK1	
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The Kurt J. Lesker Company NANO 36 is a standard system platform comprised of the following major subassemblies and is easily personalized to the user's unique application. This system is configured for magnetron sputtering and is designed to allow efficient interface to a glove box. This system is designed to allow the use of square substrates 100mm x 100mm or smaller and round substrates up to 150mm diameter or smaller. The system is delivered to the customer fully assembled and performance tested.

BASE SYSTEM DESCRIPTION

PROCESS CHAMBER

- Removable and reconfigurable top and bottom plates on ISO 250 ports (10" tube)
- · Horizontally oriented cylindrical stainless steel chamber body
- Spring-loaded, pendulum style, full-access, aluminum front door
- Appropriate pumping, process, gauging and instrumentation ports are included
- Quantity (2) viewports included in the chamber door. Viewports each have 1.26" Ø viewing area.

VACUUM PUMPING

- Pfeiffer HiPace 300 260 l/s speed control turbo pump is included in the base system
- 3.8 cfm oil sealed mechanical pump is included in the base system
- Foreline trap, mist eliminator, roughing valve, and roughing hardware provided as necessary

NOTE: Roughing pump is located remotely from system frame

NOTE: See "ROUGH VACUUM PUMPING" in Options section below for additional details and other pumping choices

VACUUM GAUGING

- Wide range vacuum gauge reads from atmosphere to 10-9 Torr
- All mounting and connection hardware, adapters, etc.

OPEN SYSTEM FRAMEWORK

- Fully enclosed system base cabinet
- Open access to the chamber
- Leveling pads and caster wheels
- Removable enclosure panels

WATER DISTRIBUTION MANIFOLD

- Manual shut off valve at manifold
- NPT connections (inlet and outlet), metric adapters supplied when appropriate

GAS AND PNEUMATIC DISTRIBUTION

- Inert Vent/Purge gas, compression fitting inlet
- Compressed air (pneumatics), compression fitting inlet
- Process gas, metal face seal inlet(s), metric adapters supplied when appropriate

POWER DISTRIBUTION

- Single service drop, 208-240VAC, 50-60Hz, single phase, 3-wire
- Amperage rating based on selected components
- Component wiring is routed to a centralized power distribution module
- EMO protection
- · Appropriate safety interlocks
- NOTE: A dedicated earth ground is required
- NOTE: If components dictate, three phase, 5-wire service may be necessary

KJLC eKLipse BASE SYSTEM CONTROL

- Laptop User Interface
- · Laptop facilitates monitoring and manual actuation of vacuum and deposition process components
- UI Navigation and Title Panel: Visual display and control of System status messages, operation mode, and system abort
- --Vacuum Screen: Visual display of valve position, pump status and vacuum status
- --Deposition Screen: Indication of shutter position, deposition source control
- --Gas Screen: Mass flow controller modes, gas valve status, pressure measurement and control display
- --Motion Screen: Substrate rotation speed, and start/stop
- --Cooling Screen: Water flow switch status where applicable
- --Heating Screen: Temperature setpoints & control parameters, PID and Tuning features
- Automatic pumpdown and vent recipes

DOCUMENTATION

- Customer drawing package (including general assembly, vacuum schematic, water flow schematic, and electrical schematics)
- Operation and component manuals provided in English

WARRANTY AND LIABILITY

- 12-month standard warranty as described in Kurt J. Lesker Company Standard Terms and Conditions of Sale
- KJLC is not liable for any indirect or consequential damages; KJLC liability shall in no event exceed the amount paid by customer to KJLC for the products described in this document

FACTORY TESTING AND COMPLIANCE

- The System is factory tested to comply with the standard NANO 36 System Performance Specifications (SPS) per attached Appendix A
- These will be the only specifications required to meet system compliance and acceptance.
- The customer will be supplied with applicable testing documentation
- No process guarantees of any kind are offered or implied with the system
- The system is manufactured in accordance to CE standards and can be CE marked for an additional cost

SYSTEM PLACEMENT, INSTALLATION AND TRAINING

- · Customer is responsible for uncrating, placement and connection of the system at the customer's facility
- Customer is responsible to provide and connect all required utilities including but not limited to compressed air, water, process/vent gas, electric, and dedicated earth ground. Detailed specifications will be provided prior to system shipment
- No spare parts are included with the base system unless specifically stated in this quotation

Base System Price

\$51,000

SYSTEM OPTIONS AND UPGRADES:

NOTE: If an option is selected, the system price will reflect the selection. Options not selected will not be included in the system.

ROUGH VACUUM PUMPING OPTIONS

RP7 1 KJLC 3.8 cfm oil-sealed mechanical roughing pump and foreline valve \$0 INCLUDED IN BASE

NOTE: Roughing pump is located remotely from system frame

BASE FLANGE OPTIONS

BF17 1 (3) GUN SPUTTER FLANGE \$0 INCLUDED IN BASE

• Allows the use of up to (3) 2" or 3" sputter sources

MAGNETRON SPUTTERING OPTIONS

COLIPCE POSITION

KJLC TORUS® Mag Keeper

- Up to three 2", or 3" TORUS® magnetron sputtering sources mounted via KJLC vacuum coupling
- Typical source to substrate distance of 4"-6" (102-152mm), manually adjustable
- Low profile CDS (Compact Dome Shutter) effectively eliminates cross contamination between adjacent sputter sources.
- Flex mount assembly for Torus® source to provide ex-situ tilt capability included
- No Anode Shield or Target Clamp Assembly yields quick target change capability and eliminates potential for debris build up and flaking
- High Vacuum and UHV Compatible
- Accepts up to 0.375" thick (non-magnetic) targets with a 3" cathode
- Accepts up to 0.250" thick (non-magnetic) targets with a 2" cathode
- Low operating pressure capability ≥ 0.5mTorr

• Permits sequential operation of attached cathodes

NOTE: Not compatible with RF supply

• No deposition materials are included unless specifically stated in this offer

NOTE: Source quantity and option selected may limit flex capability

SOURCE POS	HION			
1 MS1	1	TORUS® Mag Keeper 2", standard strength magnet assembly	\$7,100	\$7,100
2 MS0		SELECT SOURCE HERE USING DROPDOWN	\$0	NOT SELECTED
3 MS0		SELECT SOURCE HERE USING DROPDOWN	\$0	NOT SELECTED
MAGNETRO	N SPUT	TERING SOURCE POWER SUPPLIES		
PS1	1	KJLC 300W RF power supply with automatic matching network and controller Note: Limit of three available RF Power supplies	\$12,700	\$12,700
		PS1 WILL POWER THE FOLLOWING SOURCES src 1 src 2 src 3		
PS0		SELECT POWER SUPPLY	\$0	NOT SELECTED
		PS2 WILL POWER THE FOLLOWING SOURCES src 1 src 2 src 3		
PS0		SELECT POWER SUPPLY	\$0	NOT SELECTED
		PS3 WILL POWER THE FOLLOWING SOURCES		
PO1		Multi-position DC switch • Allows a power supply to drive up to three sputter cathodes	\$3,500	NOT SELECTED

SUBSTRATE	E FIXTUR	E AND MANIPULATION		
SF19	1	 Rotation Variable speed, motor driven rotating platen (up to 20 rpm) Accommodates a 150mm substrate NOTE: Not compatible with heating or cooling 	\$1,250	\$1,250
SO1		Substrate shutter • 150mm maximum substrate shutter	\$3,700	NOT SELECTED
PROCESS P	RESSURE	CONTROL		
PC4	1	Upstream Pressure Control (used with Magnetron Sputtering) VAT 3-position gate valve • One (1) Fujikin FCST1000F flow controller (0-100 sccm), all cables, and PID upstream pressure control electronics • One (1) Inficon CDG025D Capacitance Manometer 100 mTorr (0.13 mbar) pressure transducer • Orbitally welded gas lines provide maximum vacuum integrity • All MFC's will be calibrated for N2. NOTE: This option is required with magnetron sputtering	\$9,200	\$9,200
PC2	1	 Additional process gas channel (one available) Fujikin FCST1000F Mass flow controllers MFC's will be calibrated for (0-20 sccm) All MFC's will be calibrated for N2. 	\$2,800	\$2,800
FILM THICK	(NESS CC	ONTROL		
FT0 CO1		SELECT MONITOR OR CONTROL USING DROPDOWN Single standard crystal sensor	\$0 \$1,800	NOT SELECTED NOT SELECTED

COMPUTER CONTROL AND SOFTWARE

CC1 eKLipse™ ADVANCED Control \$12,100 NOT SELECTED

Includes all items detailed in KJLC eKLipse BASE Computer Control, plus:

- Provides for automated process control
- Standard Chart Recorder (plots up to 10 signals or "pens" simultaneously) and datalogging (.csv file)
- Graphical Recipe Builder generates a recipe via mouse or touchscreen selectable user interface components
- Recipe Database Screen provides selection & editing of stock recipes, with copy functionality for modification of existing & saving of new recipes
- Programming/control via a keyboard/touch pad or pop-up window on touch screen
- Supports multiple user accounts and password levels with custom security access for recipes and screens
- Ability to export/import recipes from and any KJLC tool running eKLipse Computer control with similar components and identical deposition techniques
- System event log captures all user login/logout events, all recipes executed, and system status messages
- Provides access to KJLC and user created recipes
- E-mail and Twitter equipment status notifications upon request (pressure, recipe, preventative maintenance etc.)

NOTE: System must be connected to an internet access point

TOTAL SYSTEM PRICE / TERMS AND CONDITIONS:

Total system price with options as selected (FOB Shipping Point, Prepaid & Add): \$84,050

Crate fee: \$1,000

Estimated Freight and Handling Charges: \$1,500

Estimated Total: \$86,550

SHIPMENT: 14-16 weeks after KJLC acceptance of order and receipt of first progress payment. Please note that shipment date is subject to review at time of order. Customer is responsible for all freight, crating and handling charges.

TERMS: Click here for LEF-203 KJLC Standard Terms and Conditions of Sale

Kurt J. Lesker Company Standard Terms and Conditions of Sale (LEF-203) shall apply to, and are incorporated by this reference into, the agreement(s) for the transaction(s) proposed or described in this document. These Terms and Conditions are available at the link above and are also available directly through the Kurt J. Lesker Company website at www.lesker.com. They can also can be obtained by email request to sales@lesker.com or by calling 1-800-245-1656.

PAYMENT: KJLC Standard Progress Payments will apply:

- 30% Net 30 days with order acceptance
- 60% Net 30 days upon shipment
- 10% Net 45 days after shipment (or, when applicable, Net 30 days after KJLC startup and training). Note: If a customer delays shipment or the startup and training visit beyond 30 days, then A) half of this progress payment will become due immediately, B) equipment warranty will begin immediately, and C) storage fees may apply. KJLC will issue a written notice.

NOTE: All prices are in US Dollars

No duty or taxes are included

Prices valid for 30 days

Appendix A - SPS

2017 Nano Performance Specifications

The System will comply with the Kurt J. Lesker Company (KJLC) standard Specifications (SPS) as follows. These will be the only specifications required to meet system compliance.

Reference SQ_162190MK1 for configurations and options selected and purchased. Some options may limit performance specifications.

Vacuum Performance

	Process Chamber (PC) Pumping (ref Note 1)							
	Torr	5.0E-05	1.0E-05	5.0E-06	5.0E-07	5.0E-08	Q_162190MK	1
1	mbar	6.7E-05	1.3E-05	6.7E-06	ephen M. Spa	6.7E-08		
	260l/s				(775) 784-6019			
	Turbopump			•				

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Note 1

Base Pressure is defined as the lowest observed pressure achieved in a clean, dry, properly conditioned chamber after a minimum of 12 hours of pumping. The base pressure value referenced is the minimum base pressure achieved.

Deposition Source Performance

	Magnetron Sputtering Sources (ref Note 2)					
		Uniformity	<=+/-2.5%	<=+/-3%	<=+/-5%	<=+/-7.5%
2	Torus® Sputtering Sources, RF Power, 150mm Wafer				•	
	Torus® Sputtering Sources, DC/PDC Power, 150mm Wafer				•	

Note 2	Torus® sources are operated at typical sputtering pressures (< 20 mTorr Target run with RF Power, film thickness >=500Å. Al Target run with DC run with High Strength Torus® & DC Power, film thickness >=1500Å.	
Note 3	All Films are measured on a properly calibrated Profilometer, Reflectometer or Ellipsometer (if applicable). Measurement points are taken starting at the center of the substrate and then radially outward every 0.5 inches (12.7mm), nominally (reference figure to the right). Uniformity calculation formula is: ((Max - Min) / (2 x Avg)) x 100% with a 0.2 inch (5mm) edge exclusion.	Circular and Square Reference Substrate For Visual Reference Only, Not an indication of actual substrate size